

Title (en)
APPARATUS FOR BUMP-PLATING CHIPS

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EP 0283681 B1 19920506 (DE)

Application
EP 88101499 A 19880202

Priority
DE 3705727 A 19870223

Abstract (en)
[origin: EP0283681A1] The object is to design a plating apparatus for producing finely structured, thick metal depositions on semiconductor wafers. At the same time, it is required that, in spite of an unfavourable starting base, the bump surface should be virtually flat and, in addition, a uniformity of +/- 1.0 μm should be achieved for the bump height. Furthermore, the plating apparatus must ensure reproducible, uniformly good metal deposition over many months. <??>To achieve this object, a plating cell having anode, cathode and shielding ring is used for the purpose of suspension in a plating bath. This cell consists of a plastic tube whose lower opening is provided with the anode surface and whose upper opening is covered by a wafer holder with the semiconductor wafer. The plating apparatus furthermore includes an active carbon filtering system adjusted for the levelling effect. <??>The field of application is micropack technology. <IMAGE>

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C25D 7/12

IPC 8 full level
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CPC (source: EP US)
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Cited by
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EP 0283681 A1 19880928; **EP 0283681 B1 19920506**; DE 3870685 D1 19920611; JP H044399 B2 19920128; JP S63216998 A 19880909; US 4906346 A 19900306

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